

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "DMD_P3P3V" represents connection to the +3.3V digital power plane.
2. The netname "DMD_P2P5V" represents connection to the +2.5V digital power plane.
3. The netname "DMD_P1P8V" represents connection to the +1.8V digital power plane.
4. The symbol ∇ represents connection to the digital ground plane.
5. A "Z" suffix on a signal name indicates an active low signal.
6. All components with designators "U", "D", "Y" and "Q" are electrostatic discharge sensitive.
7. All resistor values are in ohms, 1/16W and 5% unless otherwise specified.

Z PCB1



PCB, Automotive DLP 0.3 S450 DMD
DLP021
2514104



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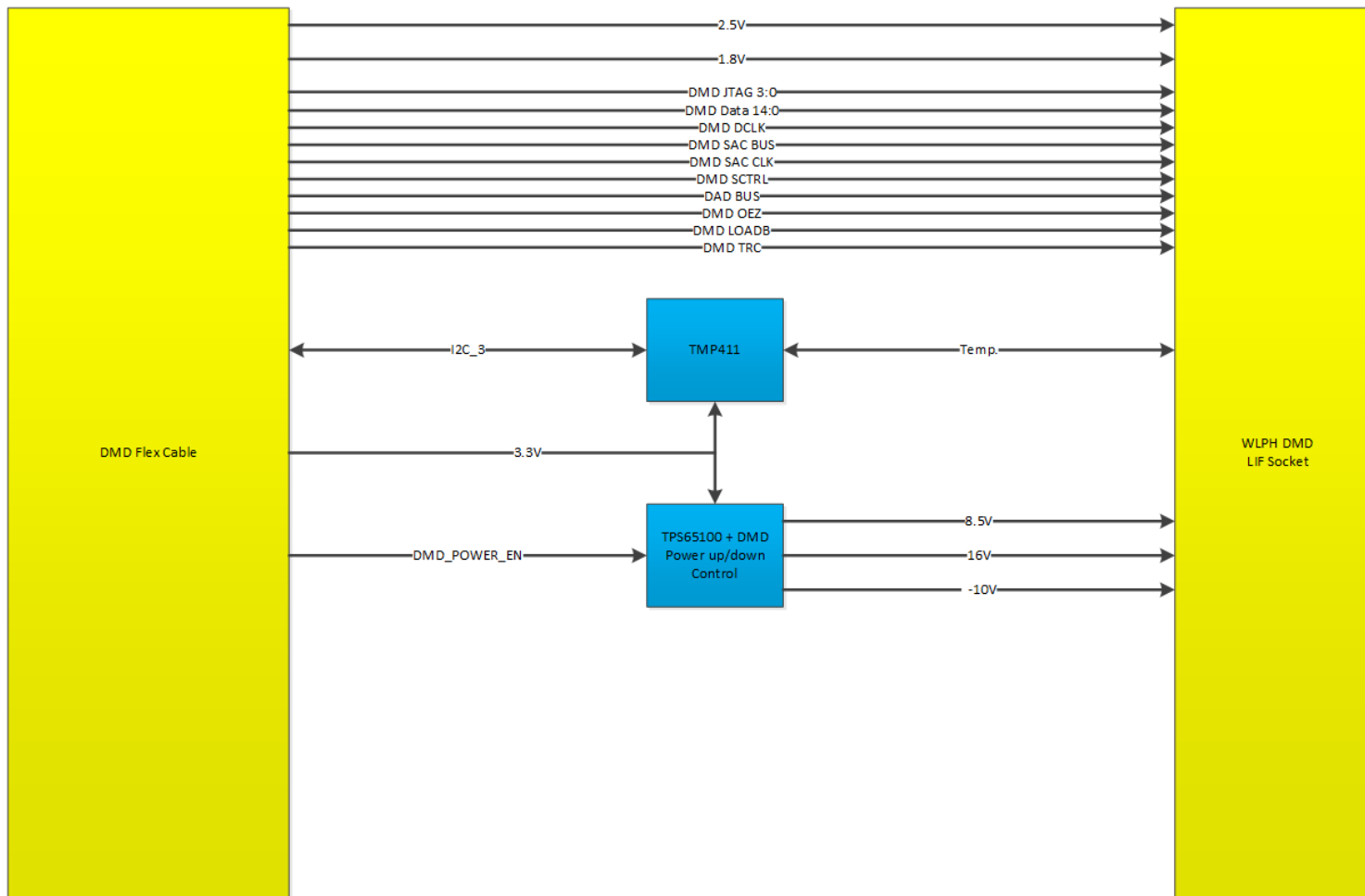
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REVISIONS

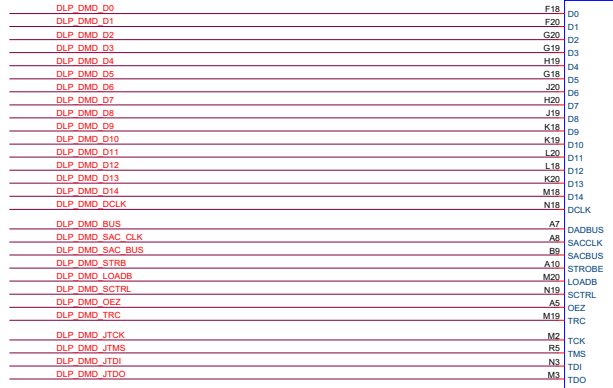
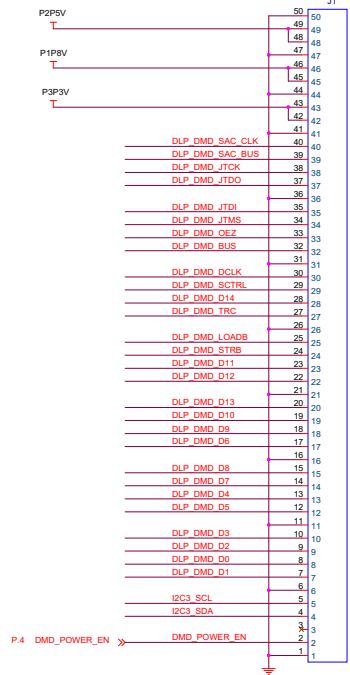
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	10/29/14	10/29/14
B	Changed heater components to DNI Added PCB.	3/22/18	3/22/18
C	Removed heater components.	7/18/18	7/18/18

	DWN	John Cooper	DATE	10/29/14	TEXAS INSTRUMENTS <small>© COPYRIGHT 2014 TEXAS INSTRUMENTS ALL RIGHTS RESERVED</small>
	ENGR	John Cooper			
	SYST	Jeff Farris			
	PRJ	Jason Thompson			
					TITLE
					Schematic, Automotive HUD 3 S450 DMD Board
					DLP021 DLP3030Q1EV2H
					D DRAWING NO 2514103 REV C
NEXT ASSY	USED ON				SCALE
APPLICATION		SW	Cadence Capture 16.6		SHEET 1 of 4

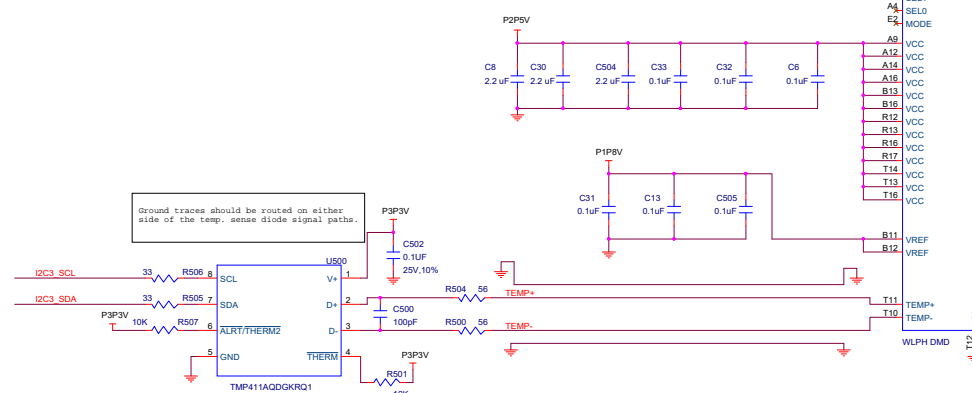
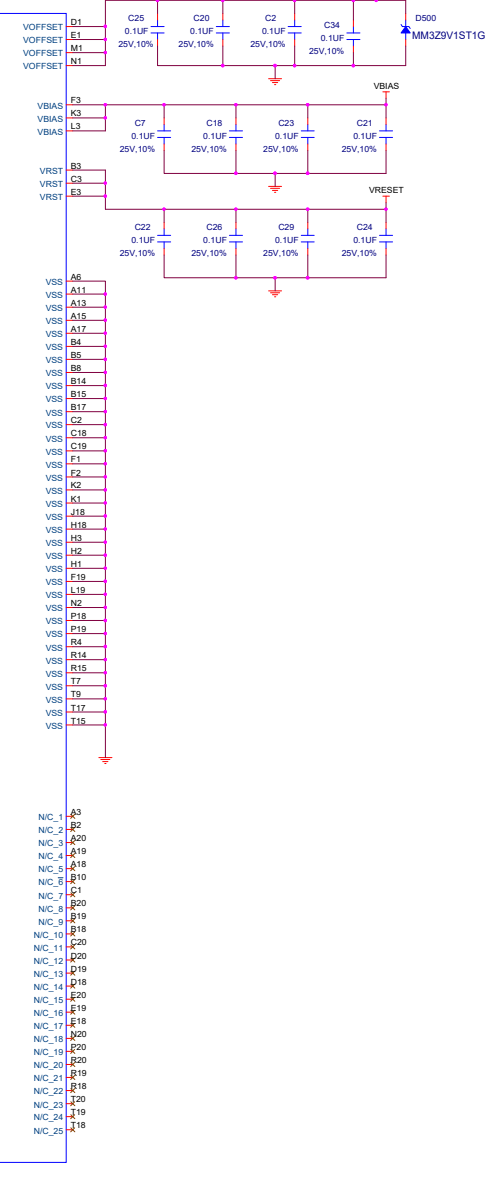


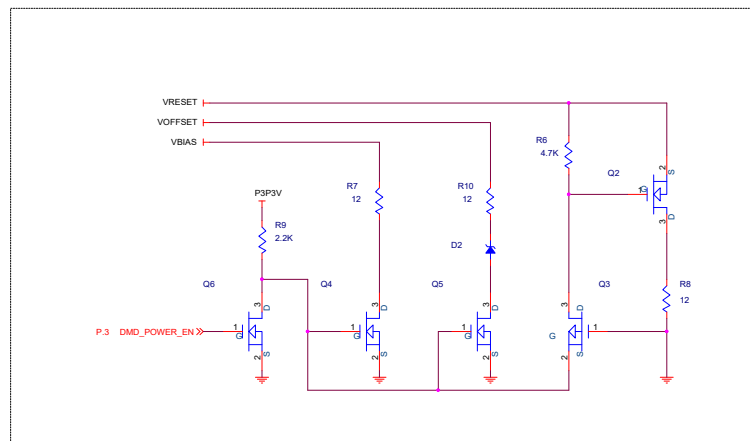
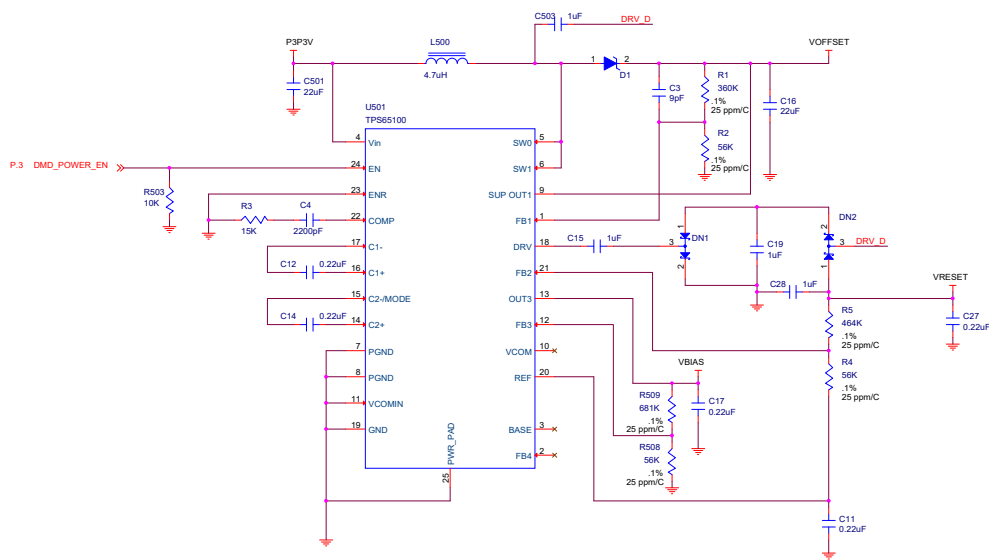
DMD BLOCK DIAGRAM

DMD Connector



.3 S450 DMD LIF SOCKET





This circuit is used to keep the power up and power down sequencing on the DMD reset voltages in spec.